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1 Applications of newly developed positive photosensitive block copolyimides to CSPs

Matsumoto, S.; Xing Zhou Jin; Fukushima, T.; Miyamura, M.; Itatani, H.;
 Electronics Packaging Technology Conference, 2000. (EPTC 2000). Proceeding
 3rd , 5-7 Dec 2000
 Pages:367 - 372

[\[Abstract\]](#) [\[PDF Full-Text \(720 KB\)\]](#) **IEEE CNF**
2 An adaptive neuro/fuzzy CMOS chip

Salam, F.M.A.; Erten, G.;
 Circuits and Systems, 1995. ISCAS '95., 1995 IEEE International Symposium
 on , Volume: 3 , 28 April-3 May 1995
 Pages:2329 vol.3

[\[Abstract\]](#) [\[PDF Full-Text \(104 KB\)\]](#) **IEEE CNF**
3 Micromachined silicon conformal packaging for millimeter wave systems applications

Katehi, L.P.B.; Kihm, R.T.;
 Electrical Performance of Electronic Packaging, 1998. IEEE 7th topical Meeting
 on , 26-28 Oct. 1998
 Pages:247

[\[Abstract\]](#) [\[PDF Full-Text \(44 KB\)\]](#) **IEEE CNF**
4 Radiation tolerance of prototype BTeV pixel detector readout chips

*Chiodini, G.; Appel, J.A.; Cardoso, G.; Christian, D.C.; Coluccia, M.R.; Hall, B.
 Hoff, J.; Kwan, S.W.; Mekkaoui, A.; Yarema, R.; Zimmerman, S.; Uplegger, L.*
 Nuclear Science, IEEE Transactions on , Volume: 49 , Issue: 6 , Dec. 2002

Pages:2895 - 2901

[\[Abstract\]](#) [\[PDF Full-Text \(460 KB\)\]](#) IEEE JNL

5 Heterogeneous integration of OE arrays with Si electronics and microoptics

Yue Liu;

Advanced Packaging, IEEE Transactions on [see also Components, Packaging Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions on] , Volume: 25 , Issue: 1 , Feb. 2002

Pages:43 - 49

[\[Abstract\]](#) [\[PDF Full-Text \(677 KB\)\]](#) IEEE JNL

6 Competitive learning with floating-gate circuits

Hsu, D.; Figueroa, M.; Diorio, C.;

Neural Networks, IEEE Transactions on , Volume: 13 , Issue: 3 , May 2002

Pages:732 - 744

[\[Abstract\]](#) [\[PDF Full-Text \(423 KB\)\]](#) IEEE JNL

7 GaInP/GaAs HBTs for high-speed integrated circuit applications

Ho, W.J.; Chang, M.F.; Sailer, A.; Zampardi, P.; Deakin, D.; McDermott, B.; Pierson, R.; Higgins, J.A.; Waldrop, J.;

Electron Device Letters, IEEE , Volume: 14 , Issue: 12 , Dec. 1993

Pages:572 - 574

[\[Abstract\]](#) [\[PDF Full-Text \(208 KB\)\]](#) IEEE JNL

8 GaInP/GaAs HBT's for high-speed integrated circuit applications

Ho, W.J.; Chang, M.F.; Sailer, A.; Zampardi, P.; Deakin, D.; McDermott, B.; Pierson, R.; Higgins, J.A.;

Electron Devices, IEEE Transactions on , Volume: 40 , Issue: 11 , Nov 1993

Pages:2113 - 2114

[\[Abstract\]](#) [\[PDF Full-Text \(220 KB\)\]](#) IEEE JNL

9 Heterogeneous integration of InP/InGaAsP MQW thin film edge emitters and polymer waveguides

Hung-Fei Kuo; Sang-Yeon Cho; Jokerst, N.M.;

Electronic Components and Technology, 2004. ECTC '04. Proceedings , Volume 2 , 1-4 June 2004

Pages:1537 - 1541 Vol.2

[\[Abstract\]](#) [\[PDF Full-Text \(456 KB\)\]](#) IEEE CNF

10 Equipment for placement and bonding

Rusander, F.;

The First IEEE International Symposium on Polymeric Electronics Packaging , Oct. 1997

Pages:259 - 264

[\[Abstract\]](#) [\[PDF Full-Text \(480 KB\)\]](#) IEEE CNF

11 Materials and mechanics issues in flip-chip organic packaging*Wu, T.Y.; Tsukada, Y.; Chen, W.T.;*Electronic Components and Technology Conference, 1996. Proceedings., 46th
31 May 1996

Pages:524 - 534

[\[Abstract\]](#) [\[PDF Full-Text \(1140 KB\)\]](#) [IEEE CNF](#)**12 The module controller chip (MCC) of the ATLAS pixel detector***Beccherle, R.;*Nuclear Science Symposium, 1998. Conference Record. 1998 IEEE , Volume:
14 Nov. 1998

Pages:69 - 74 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(576 KB\)\]](#) [IEEE CNF](#)**13 Development of ball bump forming technology using solder paste a new simplified CSP***Fujino, J.; Takaki, S.; Hayashi, K.; Izuta, G.; Hirota, J.;*Electronic Components and Technology Conference, 1998. 48th IEEE , 25-28
1998

Pages:442 - 447

[\[Abstract\]](#) [\[PDF Full-Text \(828 KB\)\]](#) [IEEE CNF](#)**14 A 93 MHz, X86 microprocessor with on-chip L2 cache controller***Draper, D.; Crowley, M.; Doppalapudi, U.; McFarland, H.; Mo, B.; Partovi, H.;
Puziol, D.; Scherer, A.; Tosaya, E.; Van Dyke, K.; Vuong, A.; Widigen, L.; Yip,
Yu, S.; Roth, D.;*Solid-State Circuits Conference, 1995. Digest of Technical Papers. 42nd ISSCC
1995 IEEE International , 15-17 Feb. 1995

Pages:172 - 173, 360

[\[Abstract\]](#) [\[PDF Full-Text \(756 KB\)\]](#) [IEEE CNF](#)**15 A wafer-scale FFT processor featuring a repeatable building block***Yamashita, K.; Kanasugi, A.; Hijiya, S.; Goto, G.;*Wafer Scale Integration, 1989. Proceedings., [1st] International Conference o
5 Jan. 1989

Pages:299 - 307

[\[Abstract\]](#) [\[PDF Full-Text \(396 KB\)\]](#) [IEEE CNF](#)

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